

TYPICAL DEVICE CHARACTERISTICS

MAXIMUM RATINGS @ 25°C Unless Otherwise Specified								
PARAMETER	SYMBOL	VALUE	UNITS					
Peak Pulse Power (tp = 8/20μs) - See Figure 1	P _{PP}	500	Watts					
Operating Temperature	T _L	-55 to 150	°C					
Storage Temperature	T _{stg}	-55 to 150	°C					

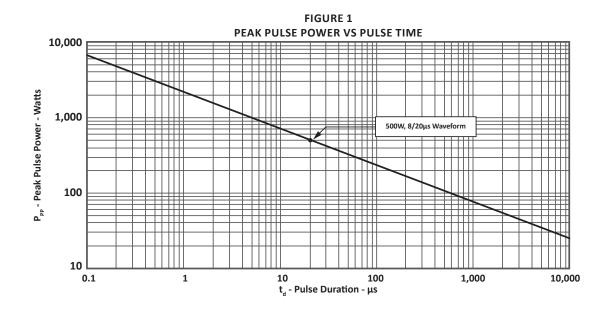
	ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified									
PART NUMBER (Note 1)	DEVICE MARKING	RATED STAND-OFF VOLTAGE V _{WM} VOLTS	MINIMUM BREAKDOWN VOLTAGE (Note 2) @ 1mA V _(BR) VOLTS	MAXIMUM CLAMPING VOLTAGE (Fig. 2) @ $I_p = 1A$ V_c VOLTS	MAXIMUM CLAMPING VOLTAGE (Fig. 2) @ $I_p = 5A$ V_c VOLTS	MAXIMUM LEAKAGE CURRENT @V _{WM} Ι _D μΑ	TYPICAL CAPACITANCE @0V, 1MHz C pF			
PSOT03LC	03L	3.3	4.0	7.0	9.0	125	5			
PSOT05LC	05L	5.0	6.0	9.8	11.0	20	5			
PSOT08LC	08L	8.0	8.5	13.4	15.0	10	5			
PSOT12LC	12L	12.0	13.3	19.0	23.0	1	5			
PSOT15LC	15L	15.0	16.7	24.0	28.0	1	5			
PSOT24LC	24L	24.0	26.7	43.0	46.0	1	5			
PSOT36LC	36L	36.0	40.0	51.0	68.0	1	5			

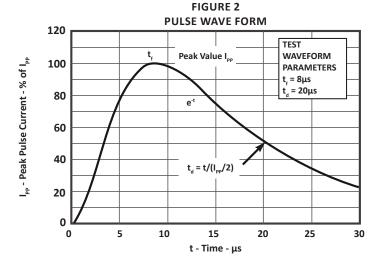
NOTES

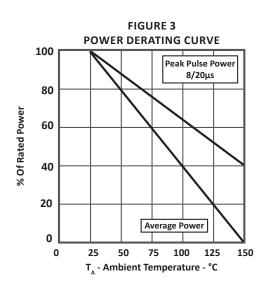
^{1.} Positive potential is applied from pin 1 to 2; pin 2 is ground.

^{2.} Do not test or surge from pin 2 to 1. PIV typically greater than 100V for rectifier diode.

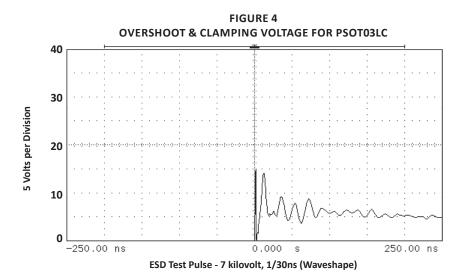
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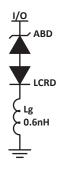


TYPICAL DEVICE CHARACTERISTICS



SPICE MODEL

FIGURE 1 SPICE MODEL FOR



ABD - Avalanche Breakdown Diode (TVS) LCRD - Low Capacitance Rectifier Diode Lg - Lead Inductance

TABLE 1 - SPICE PARAMETERS								
PARAMETER	UNIT	ABD(TVS)	LCRD					
BV	V	See Table 2	200					
IBV	μΑ	1	0.01					
C _{jo}	pF	See Table 2	5					
I _s	А	See Table 2	1E-14					
Vj	V	0.6	0.6					
М	-	0.33	0.33					
N	-	1	1					
R _s	Ohms	See Table 2	0.31					
TT	S	1E-8	1E-9					
EG	eV	1.11	1.11					

TABLE 2 - ABD SPECIFIC SPICE PARAMETERS								
PART NUMBER	B _v (VOLTS)	C _{io} (pF)	I _s (AMPS)	Rs(OHMS)				
PSOT03LC	4.5	438	1E-11	0.21				
PSOT05LC	6.0	284	1E-11	0.14				
PSOT08LC	8.5	146	1E-11	0.28				
PSOT12LC	13.3	123	1E-13	0.40				
PSOT15LC	16.7	102	1E-13	0.52				
PSOT12LC	26.7	61	1E-13	1.54				

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APPLICATION INFORMATION

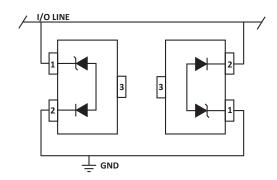


FIGURE 1 - COMMON MODE I/O PORT PROTECTION

Two PSOTxxLC devices used in parallel. Circuit connectivity is as follows:

- I/O Line connected to Device 1, Pin 1.
- I/O Line connected to Device 2, Pin 2.
- Device 1, Pin 2 connected to ground.
- Device 2, Pin 1 connected to ground.
- Device 1 and 2, Pin 3 not connected.

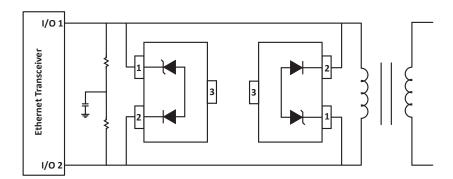


FIGURE 1 - DIFFERENTIAL MODE ETHERNET PROTECTION

Two PSOTxxLC devices used in parallel. Circuit connectivity is as follows:

- I/O Line 1 connected to Device 1, Pin 1.
- I/O Line 1 connected to Device 2, Pin 2.
- I/O Line 2 connected to Device 1, Pin 1.
- I/O Line 2 connected to Device 2, Pin 2.
- Device 1 and 2, Pin 3 not connected.

CIRCUIT BOARD RECOMMENDATIONS

Circuit board layout is critical for electromagnetic compatibility protection. The following guidelines are recommended:

- The protection device should be placed near the input terminals or connectors, the device will divert the transient current immediately before it can be coupled into the nearby traces.
- The path length between the TVS device and the protected line should be minimized.
- All conductive loops including power and ground loops should be minimized.
- The transient current return path to ground should be kept as short as possible to reduce parasitic inductance.
- · Ground planes should be used whenever possible. For multilayer PCBs, use dedicated ground planes



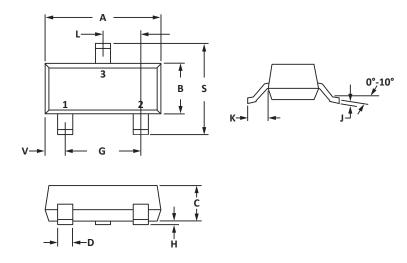


SOT-23 PACKAGE INFORMATION

OUTLINE DIMENSIONS								
DIM	MILLIN	IETERS	INCHES					
	MIN	MAX	MIN	MAX				
А	2.80	3.04	0.110	0.120				
В	1.20	1.40	0.047	0.055				
С	0.89	1.11	0.035	0.044				
D	0.37	0.50	0.015	0.020				
G	1.78	2.04	0.070	0.081				
Н	0.013	0.100	0.001	0.004				
J	0.085	0.177	0.003	0.007				
К	0.45	0.60	0.018	0.024				
L	0.89	1.02	0.035	0.040				
S	2.10	2.50	0.083	0.098				
V	0.45	0.60	0.018	0.024				

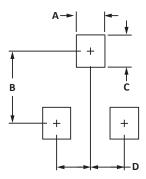


- 1. Controlling dimension: inches.
- 2. Dimensioning and tolerances per ANSI Y14.5M, 1985.
- 3. Pin 3 is the cathode (Unidirectional Only)
- 4. Dimensions are exclusive of mold flash and metal burrs.

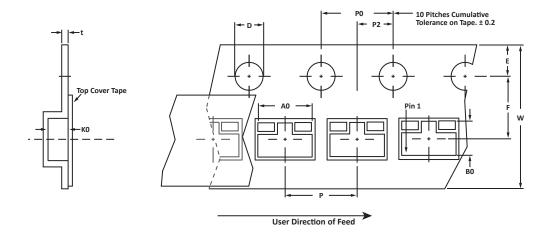


PAD LAYOUT DIMENSIONS								
DINA	MILLIN	IETERS	INCHES					
DIM	MIN	MAX	MIN	MAX				
А	0.71	0.97	0.028	0.038				
В	1.88	2.13	0.074	0.084				
С	0.71	0.97	0.028	0.038				
D	0.81	1.07	0.032	0.042				
NOTES	NOTES							

1. Controlling dimension: inches.



TAPE AND REEL



SPECIFICATIONS												
REEL DIA.	TAPE WIDTH	Α0	В0	КО	D	E	F	W	P0	P2	Р	tmax
178mm (7")	8mm	3.15 ± 0.10	2.77 ± 0.10	1.30 ± 0.10	1.55 ± 0.10	1.75 ± 0.10	3.50 ± 0.05	8.00 ± 0.30	4.00 ± 0.10	2.00 ± 0.05	4.00 ± 0.10	0.228

NOTES

- 1. Dimensions are in millimeters.
- 2. Surface mount product is taped and reeled in accordance with EIA-481.
- 3. Suffix T7 = 7" Reel 3,000 pieces per 8mm tape.
- 4. Suffix T13 = 13" Reel 10,000 pieces per 8mm tape.
- 5. Marking on Part marking code (see page 2) and date code.

Package outline, pad layout and tape specifications per document number 06012.R2 8/10.

ORDERING INFORMATION								
BASE PART NUMBER (xx = Voltage)	LEADFREE SUFFIX	TAPE SUFFIX	QTY/REEL	REEL SIZE	TUBE QTY			
PSOTxxLC	-LF	-T7	3,000	7"	n/a			
PSOTxxLC	-LF	-T13	10,000	13"	n/a			
This device is only available in a Lead-Free configuration.								

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COMPANY INFORMATION

COMPANY PROFILE

In business more than 25 years, ProTek Devices™ is a privately held semiconductor company. The company offers a product line of overvoltage protection and overcurrent protection components. These include transient voltage suppressor array (TVS arrays) avalanche breakdown diode, steering diode TVS array and electronics SMD chip fuses. These components deliver circuit protection in electronic systems from numerous overvoltage and overcurrent events. They include lightning; electrostatic discharge (ESD); nuclear electromagnetic pulses (NEMP); inductive switching; and electromagnetic interference (EMI) / radio frequency interference (RFI). ProTek Devices also offers LED wafer die for ESD protection and related high frequency products. ProTek Devices is ISO 9001:2015 certified.

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